L Number	Hits	Search Text	DB	Time stamp
1	2	("5889326").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:16
2	9	("4724472" | "4970570" | "5028987" | "5422516" | "5508561" | "5611481" | "5640051" | "5640052" | "5641113").PN.	USPAT	2004/09/10 09:11
3	27	5889326.URPN.	USPAT	2004/09/10 09:12
4	3540	((257/747) or (257/759) or (257/773) or (257/779)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:17
5	5624	organic adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:17
6	60	(((257/747) or (257/759) or (257/773) or (257/779)).CCLS.) and (organic adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:28
7	113	(257/474).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:29
8	256	(257/747).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:29
-	7	semiconductor adj substrate and organic adj substrate and pad and solder and ("coefficent of thermal expansion" or cte)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:08
-	6	("5471090" | "6005292" | "6046910" | "6118181" | "6232668" | "6271597").PN.	USPAT	2002/11/05 12:59
-	0	6310403.URPN.	USPAT	2002/11/05 13:02
-	6	("5471090" | "6005292" | "6046910" | "6118181" | "6232668" | "6271597").PN.	USPAT	2002/11/05 13:02
-	9	("3842189" | "4056681" | "4647959" | "4949148" | "5214308" | "5302854" | "5331513" | "5528461" | "5657207").PN.	USPAT	2002/11/05 13:02
-	5	6046910.URPN.	USPAT	2002/11/05 13:03
-	4345	"coefficent of thermal expansion" or cte	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 13:16
-	31	((257/786).CCLS.) and ("coefficent of thermal expansion" or cte)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 13:06
-	1299	c4 same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 13:07

-	169	("coefficent of thermal expansion" or cte) and (c4 same solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 13:55
-	327	gigapascal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 13:16
-	19	("coefficent of thermal expansion" or cte) and gigapascal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 13:18
-	0	underfill adj material same gigapascal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 13:19
-	775	underfill adj material	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 13:19
-	188	("coefficent of thermal expansion" or cte) and (underfill adj material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 13:19
-	143	conductive adj pad and solder and bump and c4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 13:41
-	1235	(257/786).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 09:10
-	195	c4 and solder and ("coefficent of thermal expansion" or cte)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 13:51
-	7841	(lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 14:46
-	20	("coefficent of thermal expansion" or cte) and (c4 same solder) and ((lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 13:56
-	2570	(lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn) and c4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 15:00
-	14566	flip adj chip or flipchip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 14:47
-	386	((lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn) and c4) and (flip adj chip or flipchip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 14:47

-	245	((lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn)) and c4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 15:01
-	69	larger near pad and smaller near pad and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/11 10:14
-	6	("4673772" | "5616520" | "5761048" | "5859407" | "5907187" | "6093964").PN.	USPAT	2003/11/11 10:23
-	1	6285083.URPN.	USPAT	2003/11/11 10:25
-	2	6274474.URPN.	USPAT	2003/11/11 10:32
-	0	beriner.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:41
-	670	bernier.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:41
-	7	solder adj ball and bernier.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:43
-	6925	carey.in. or gramatzki.in. or homa.in. or langevin.in. or tran.in. or white.in	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:44
-	20	solder adj ball and (carey.in. or gramatzki.in. or homa.in. or langevin.in. or tran.in. or white.in)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:45
-	57	5075965.URPN.	USPAT	2003/11/18 13:50
-	0	6330967.URPN.	USPAT	2003/11/18 13:54
-	25	("4545610" | "5060844" | "5075965" | "5161729" | "5221038" | "5234152" | "5372298" | "5429292" | "5470787" | "5473814" | "5580668" | "5591941" | "5634268" | "5639696" | "5675889" | "5729896" | "5796591" | "5808853" | "5825629" | "5912505" | "5953623" | "5965945" | "6121069" | "6130476" | "6162660").PN.	USPAT	2003/11/18 13:54
-	27	organic adj substrate and (bump or electrode or pad) and solder adj ball and semiconductor adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 14:30